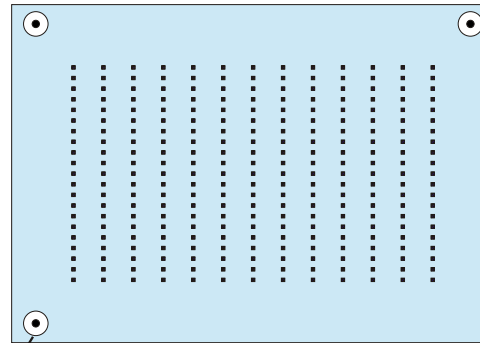
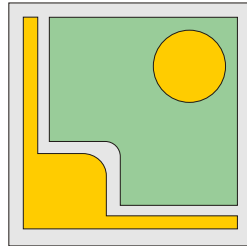


A semiconductor is picked from the wafer and placed on an adhesive NETO tape

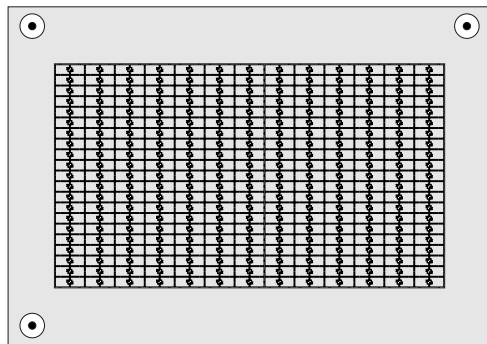


The semiconductors are positioned on the NETO tape in pattern corresponding to the cavities of the chip carrier.

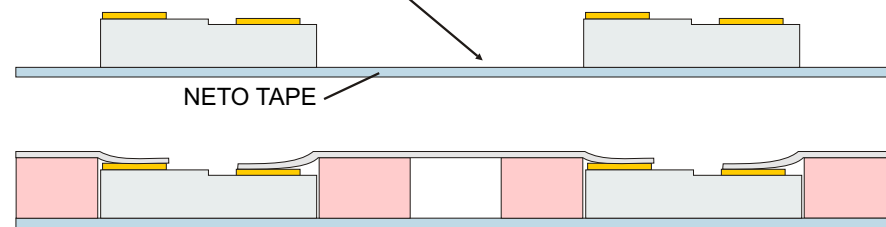
LOCAL OPTICAL FIDUCIALS

ADHESIVE SURFACE

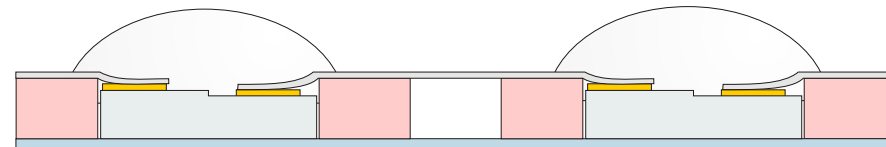
NETO TAPE



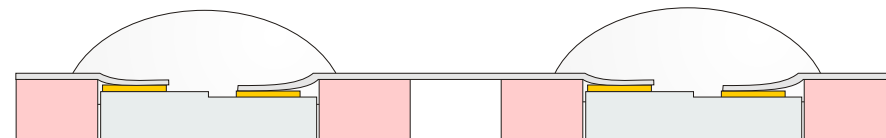
SEMICONDUCTOR FRAME CIRCUIT SIDE



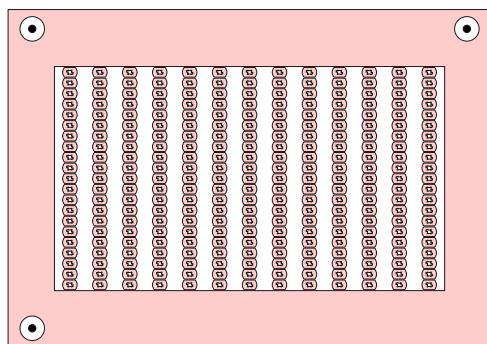
THE CHIP CARRIER IS PLACED OVER THE SEMICONDUCTORS AND AFFIXED TO THE ADHESIVE TAPE CARRIER



THE SEMICONDUCTORS ARE ULTRASONICALLY BONDED TO THE CIRCUITS AND THE DIE SITE IS CONFORMALLY COATED



THE ADHESIVE SURFACE OF THE TAPE IS ANNULLED WITH ULTRA VIOLET LIGHT AND THE TAPE IS STRIPPED FROM THE ASSEMBLY.



SEMICONDUCTOR FRAME CAVITY SIDE